# TOSHIBA

#### **TOSHIBA LED lamps**

# TL12W02-D(T30)

#### O Surface-Mount Devices

- 10.5 (L) mm × 5.0 (W) mm × 2.1 (H) mm
- High luminous flux: 90 lm(typ.) @250 mA
- Color: white
- Topr / Tstg: -40 to 100°C
- Reflow-solderable
- Standard embossed tape packing: T30 (500 pcs/reel)

24-mm tape reel

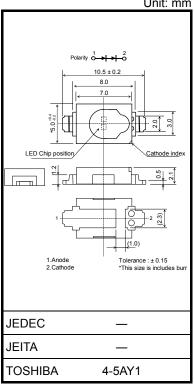
Applications : general lighting

#### Color and Material

| Part Number | Color | Material |
|-------------|-------|----------|
| TL12W02-D   | White | InGaN    |

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteristics       | Symbol           | Rating     | Unit |
|-----------------------|------------------|------------|------|
| Forward Current       | ١ <sub>F</sub>   | 300        | mA   |
| Power Dissipation     | PD               | 2.37       | W    |
| Operating Temperature | T <sub>opr</sub> | -40 to 100 | °C   |
| Storage Temperature   | T <sub>stg</sub> | -40 to 100 | °C   |
| Junction Temperature  | Тј               | 110        | °C   |

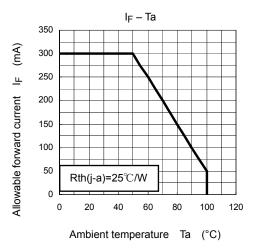


Weight: 0.30 g (typ.)

Note 1: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 2: The junction-to-ambient thermal resistance, Rth(j-a), should be kept below 25  $^\circ$ C/W so that the TL12W02-D(T30) is not exposed to a condition beyond the absolute maximum ratings. Rth(j-a): Thermal resistance from the LED junction to ambient temperature



Unit: mm

#### **Electrical Characteristics (Ta = 25°C)**

| Characteristics    | Symbol         | Test condition          | Min | Тур. | Max | Unit  |
|--------------------|----------------|-------------------------|-----|------|-----|-------|
| Forward Voltage    | VF             | I <sub>F</sub> = 250 mA | 6.3 | 6.8  | 7.9 | V     |
| Reverse Current    | I <sub>R</sub> | $V_R = 4V$              | _   | _    | 40  | μA    |
| Thermal Resistance | Rth(j-s)       | I <sub>F</sub> = 250 mA |     | 10   | _   | ° C/W |

#### Note 3: VF rank classification

| sification  |        |                                |      |     | Ta=25°C |
|-------------|--------|--------------------------------|------|-----|---------|
| Part Number |        | Forward Voltage V <sub>F</sub> |      |     |         |
| Fait Nui    | IDEI   | Min                            | Тур. | Max | IF      |
| TL12W02-I   | D(T30) | 6.3                            | 6.8  | 7.9 |         |
|             | 1      | 6.3                            |      | 7.2 | 250     |
|             | 2      | 7.0                            |      | 7.9 |         |
| Unit        |        |                                | V    |     | mA      |

The specification on the above table is used for  $V_F$  classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

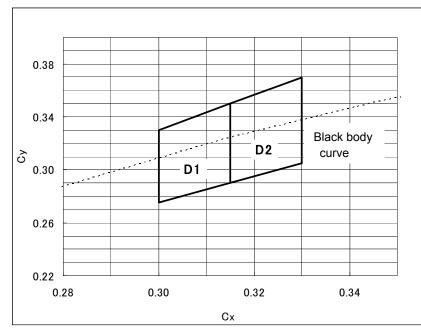
#### **Optical Characteristics (Ta = 25°C)**

| Characteristics | Symbol | Test condition          | Min      | Тур.     | Max | Unit |
|-----------------|--------|-------------------------|----------|----------|-----|------|
| Chromaticity    | Cx     | I <sub>F</sub> = 250 mA | (Note 4) |          | —   |      |
| Ghiomaticity    | Cy     | I <sub>F</sub> = 250 mA |          | (Note 4) |     | _    |
| Luminous flux   | F      | I <sub>F</sub> = 250 mA | 40       | 90       | 160 | lm   |

Note 4: The product is tested at the following chromaticity coordinate groups.

Test conditions: I<sub>F</sub>=250 mA, Ta=25°C

Accuracy: +/-0.01



|    | Сх    | Су    |
|----|-------|-------|
|    | 0.315 | 0.290 |
| D1 | 0.300 | 0.275 |
| ы  | 0.300 | 0.330 |
|    | 0.315 | 0.350 |
|    | 0.330 | 0.305 |
| D2 | 0.315 | 0.290 |
| υz | 0.315 | 0.350 |
|    | 0.330 | 0.370 |

#### Note 5: F rank classification

| Ta=25°C | • |
|---------|---|
|---------|---|

| Part Number |        |     | Luminous | s flux F |     |
|-------------|--------|-----|----------|----------|-----|
| Fait Nui    | IDEI   | Min | Тур.     | Max      | IF  |
| TL12W02-I   | D(T30) | 40  | 90       | 160      |     |
|             | E      | 40  | —        | 80       | 250 |
|             | F      | 56  | —        | 113      |     |
|             | G      | 80  | _        | 160      |     |
| Unit        |        |     | lm       |          | mA  |

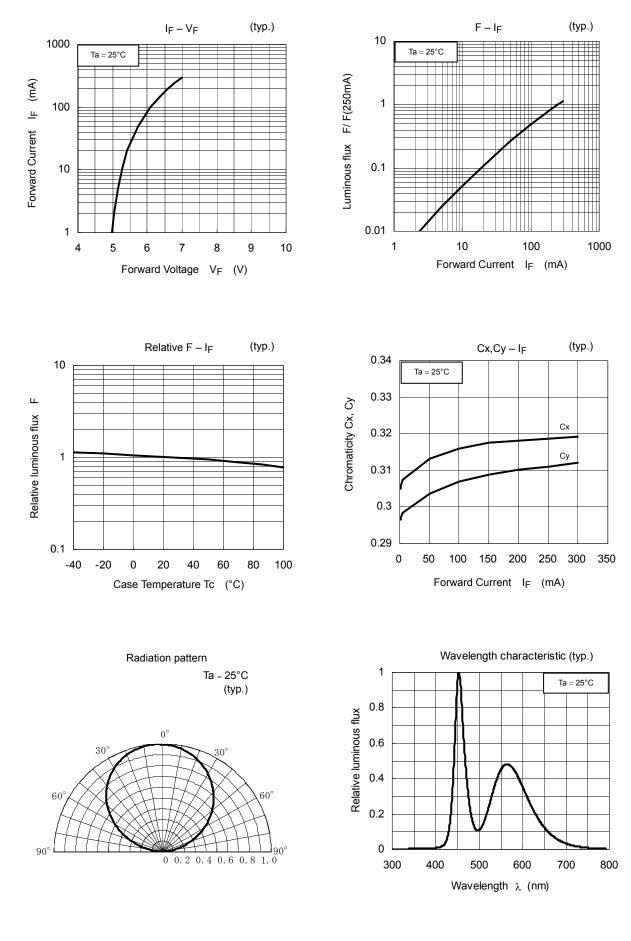
The specification on the above table is used for F classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

#### Note 6: Caution

- The product is sensitive to electrostatic and care must be fully taken when handling products. Particularly in the case that an over-voltage shall be applied, the overflowed energy may cause damage to or possibly result in destruction of the product. Users shall take absolutely secure countermeasures against electrostatic and surge when handling the product.
- This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

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#### TL12W02-D



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# Packaging

This LED device is packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

- This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5°C to 30°C Humidity: 90% (max)
- 2. After opening the moisture proof bag, the device should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel. After baking, use the baked devices within 72 hours, but perform baking only once. Baking conditions: 60±5°C, for 24 to 48 hours.
  Expiration date: 12 months from cooling date, which is imprinted on the label offixed.

Expiration date: 12 months from sealing date, which is imprinted on the label affixed.

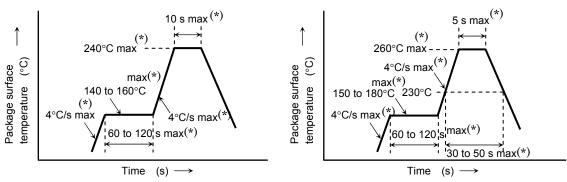
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting.
- 5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

## **Mounting Method**

#### Soldering

Reflow soldering (example)
 Temperature profile for Pb soldering (example)

Temperature profile for Pb-free soldering (example)



- The product is evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (\*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering

In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions.

Storage conditions before the second reflow soldering: 30°C, 60% RH (max)

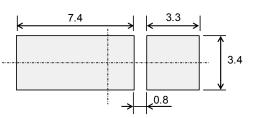
• When any soldering corrections are made manually, a hot-plate should be used . (only once at each soldering point)

| (only once at each soldering p | Joint)                                  |
|--------------------------------|-----------------------------------------|
| Temperature of a hot plate:    | $150^{\circ}C$                          |
| Soldering iron:                | $25~\mathrm{W}$                         |
| Temperature:                   | $350^{\circ}\mathrm{C} \text{ or less}$ |
| Time:                          | within $3 \mathrm{s}$                   |

• Do not perform wave soldering.

#### **Recommended Soldering Pattern**

Unit (mm)



#### Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES: (made by ASAHI GLASS)

#### **Precautions When Mounting**

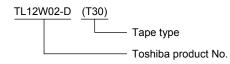
Do not apply force to the plastic part of the LED under high-temperature conditions. To avoid damaging the LED plastic, do not apply friction using a hard material. When installing the PCB in a product, ensure that the device does not come into contact with other cmponents.

#### **Tape Specifications**

#### 1. Product Number Format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

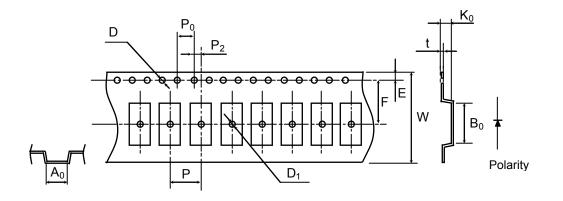
- (1) Tape Type: T30 (8-mm pitch)
- (2) Example



## 2. Tape Dimensions

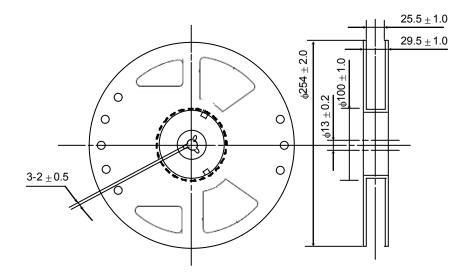
| Symbol         | Dimension | Tolerance |
|----------------|-----------|-----------|
| D              | 1.5       | +0.1/-0   |
| E              | 1.75      | ±0.1      |
| P <sub>0</sub> | 4.0       | ±0.1      |
| t              | 0.3       | ±0.05     |
| F              | 11.5      | ±0.1      |
| D <sub>1</sub> | 1.7       | ±0.1      |

| Symbol         | Dimension | Tolerance |
|----------------|-----------|-----------|
| P <sub>2</sub> | 2.0       | ±0.1      |
| W              | 24.0      | ±0.2      |
| Р              | 8.0       | ±0.1      |
| A <sub>0</sub> | 5.5       | ±0.1      |
| B <sub>0</sub> | 11.0      | ±0.1      |
| K <sub>0</sub> | 2.3       | ±0.1      |



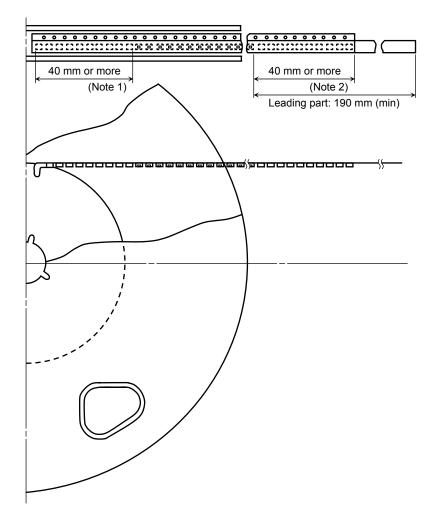
#### 3. Reel Dimensions

Unit: mm



## 4. Leader and Trailer Sections of Tape

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Note 1: Empty trailer section Note 2: Empty leader section

#### 5. Packing Form

(1) Packing quantity

| Reel   | 500 pcs |
|--------|---------|
| Carton | 500 pcs |

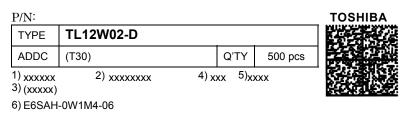
(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

#### 6. Label Format

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(1) Label contents

Shipped products are mentioned the following contents.



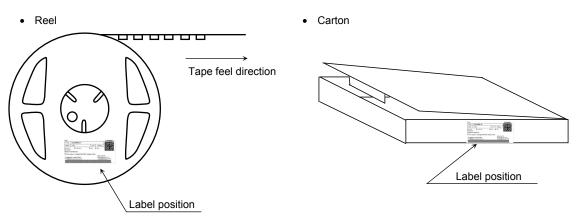
<sup>7)</sup>Use under 5-30degC/60%RH within 168h



Contents about Note section (Each example means the contents are different for each lot.)

| Information for customers use | Information for Toshiba use           |
|-------------------------------|---------------------------------------|
| 1) Lot code                   | 4) Management code                    |
| Example: 2707C2B              | Example: 715 32G                      |
| 2) Key code                   | 5) Packing quantity                   |
| Example: 12345678             | Example: 500 pcs                      |
| 3) Rank symbol                | 6) Product information                |
| Example: D2F1                 | E6SAH-0W1M4-06                        |
|                               | 7) Storage condition after opening    |
|                               | Use under 5-30 degC/60%RH within 168h |

(2) Label location



• The aluminum package in which the reel is supplied also has the label attached to center of one side.

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